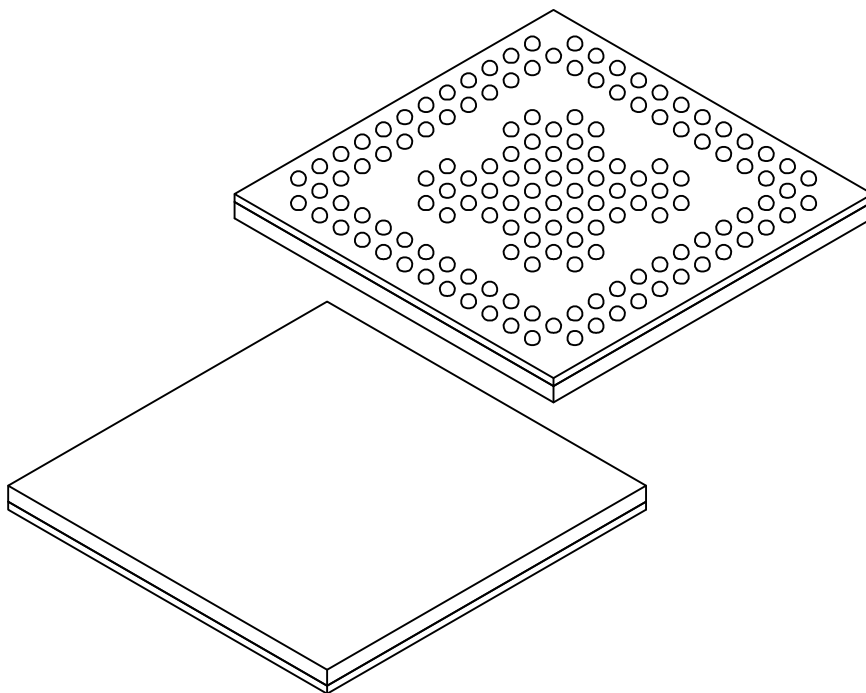


144-Ball Thin Fine-Pitch Ball Grid Array Package (LUX) - 12×12×1.19 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		144		
Pitch	e		0.80 BSC		
Overall Height	A	–	–		1.19
Ball Height	A1	0.21	0.30		–
Mold Thickness	A2	0.48	0.53		0.58
Overall Length	D		12.00 BSC		
Overall Width	E		12.00 BSC		
Ball Diameter	b	0.35	0.40		0.45

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.